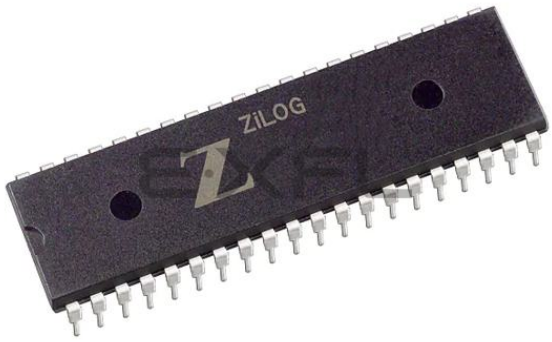

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	12MHz
Connectivity	EBI/EMI
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.620", 15.75mm)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8674312psc

Table 4. 44-Pin LQFP Pin Identification (Continued)

Pin No	Symbol	Function	Direction
18	RESET	Reset	Input
19	P35	Port 3, Pin 5	Output
20	P37	Port 3, Pin 7	Output
21	P36	Port 3, Pin 6	Output
22	P30	Port 3, Pin 0	Input
23-24	P00-P01	Port 0, Pin 0,1	Input/Output
25-26	P10-P11	Port 1, Pins 0,1	Input/Output
27	P02	Port 0, Pin 2	Input/Output
28-29	GND	Ground	
30-31	P12-P13	Port 1, Pins 2,3	Input/Output
32	P03	Port 0, Pin 3	Input/Output
33-37	P20-24	Port 2, Pins 0,1,2,3,4	Input/Output
38	DS	Data Strobe	Output
39	NC	No Connection	
40	R/$\overline{W}$	Read/Write	Output
41-43	P25-P27	Port 2, Pins 5,6,7	Input/Output
44	P04	Port 0, Pin 4	Input/Output

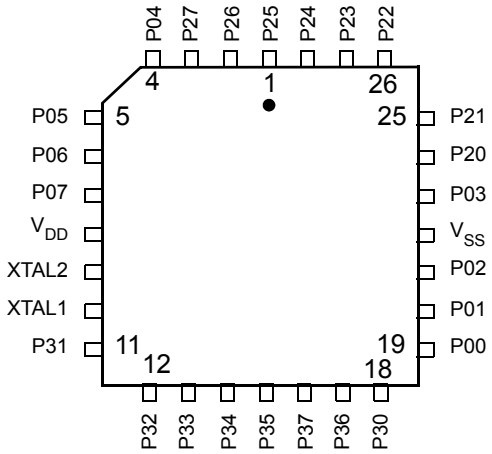


Figure 10. Standard Mode 28-Pin PLCC Pin Configuration

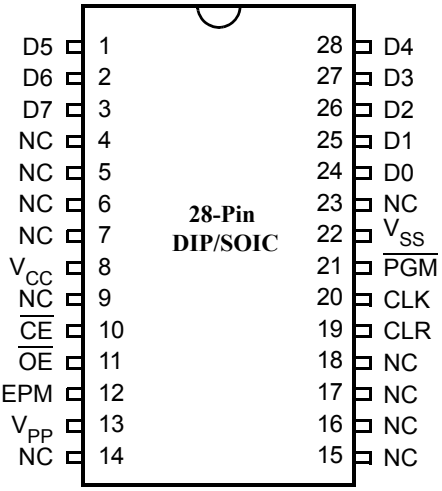


Figure 11. EPROM Programming Mode 28-Pin DIP/SOIC Pin Configuration

Electrical Characteristics

Absolute Maximum Ratings

Table 10. Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on XTAL1, P32, P33 and $\overline{\text{RESET}}$ Pins with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		1.21	W	
Maximum Allowable Current out of V_{SS}		220	mA	
Maximum Allowable Current into V_{DD}		180	mA	
Maximum Allowable Current into an Input Pin	–600	+600	µA	3
Maximum Allowable Current into an Open-Drain Pin	–600	+600	µA	4
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by $\overline{\text{RESET}}$ Pin		3	mA	

Notes
1. This applies to all pins except XTAL pins and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. This excludes XTAL pins.
4. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

Table 12. DC Electrical Characteristics T_A= -40 °C to +105 °C (Continued)

Symbol	Parameter	V_{CC} [1]	Min	Max	Typical @ 25°C	Units	Conditions	Notes
V_{OH1}	Output High Voltage	4.5V	V_{CC} -0.4		4.8	V	I_{OH} = -2.0 mA	2
		5.5V	V_{CC} -0.4		4.8	V	I_{OH} = -2.0 mA	2
V_{OL}	Output Low Voltage Low EMI Mode	4.5V		0.4	0.2	V	I_{OL} = 1.0 mA	
		5.5V		0.4	0.2	V	I_{OL} = 1.0 mA	
V_{OL1}	Output Low Voltage	4.5V		0.4	0.1	V	I_{OL} = +4.0 mA	2
		5.5V		0.4	0.1	V	I_{OL} = +4.0 mA	2
V_{OL2}	Output Low Voltage	4.5V		1.2	0.5	V	I_{OL} = +12 mA	2
		5.5V		1.2	0.5	V	I_{OL} = +12 mA	2
V_{RH}	Reset Input High Voltage	4.5V	.8 V_{CC}	V_{CC}	1.7	V		3
		5.5V	.8 V_{CC}	V_{CC}	2.1	V		3
V_{OLR}	Reset Output Low Voltage	4.5V		0.6	0.3	V	I_{OL} = 1.0 mA	3
		5.5V		0.6	0.2	V	I_{OL} = 1.0 mA	3
V_{OFFSET}	Comparator Input Offset Voltage	4.5V		25	10	mV		
		5.5V		25	10	mV		
V_{ICR}	Input Common Mode Voltage Range	4.5V	0	V_{CC} -1.5V		V		4
		5.5V	0	V_{CC} -1.5V		V		4
I_{IL}	Input Leakage	4.5V	-1	2	<1	µA	V_{IN} = 0V, V_{CC}	
		5.5V	-1	2	<1	µA	V_{IN} = 0V, V_{CC}	
I_{OL}	Output Leakage	4.5V	-1	2	<1	µA	V_{IN} = 0V, V_{CC}	
		5.5V	-1	2	<1	µA	V_{IN} = 0V, V_{CC}	
I_{IR}	Reset Input Current	4.5V	-18	-180	-112	µA		3
		5.5V	-18	-180	-112	µA		3
I_{CC}	Supply Current	4.5V		20	15	mA	@ 12 MHz	5,6
		5.5V		20	15	mA	@ 12 MHz	5,6
I_{CC1}	Standby Current HALT Mode	4.5V		6	2	mA	V_{IN} = 0V, V_{CC} @ 12 MHz	5,6
		5.5V		6	4	mA	V_{IN} = 0V, V_{CC} @ 12 MHz	5,6

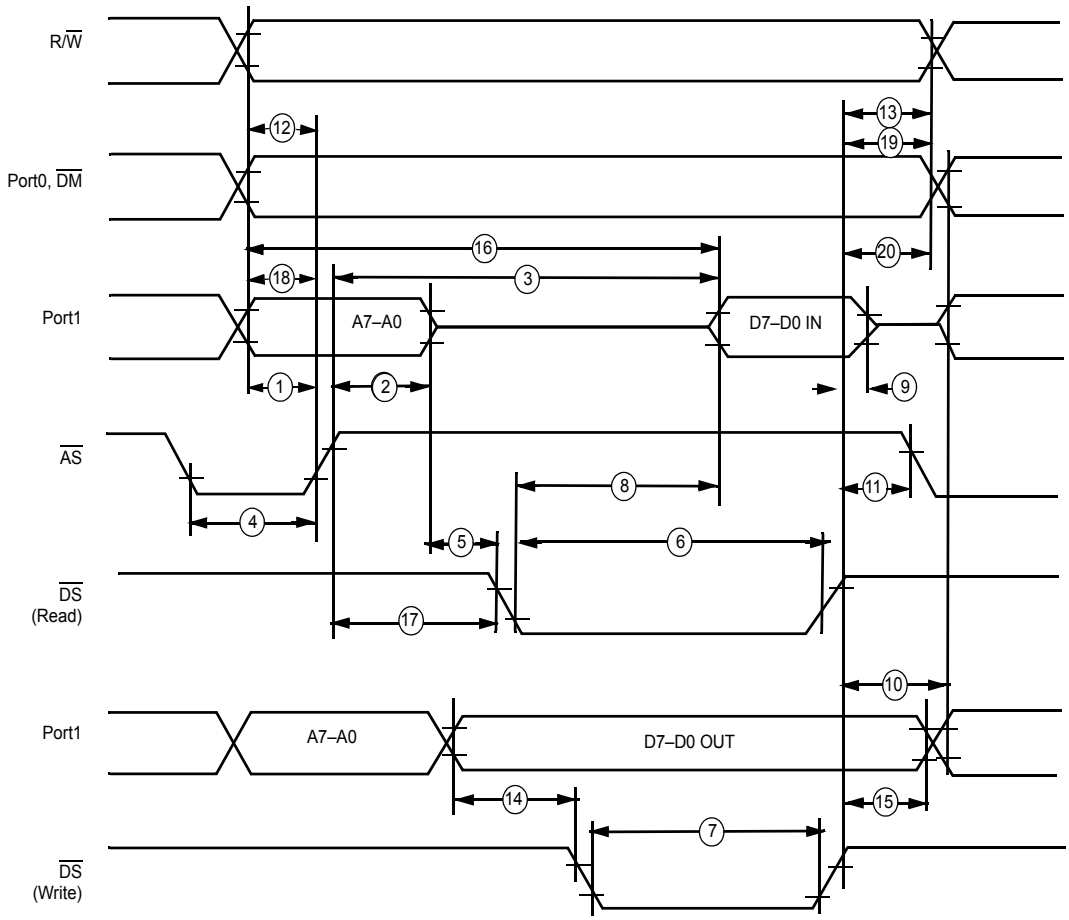


Figure 14. External I/O or Memory Read/Write Timing (Z86E43/743/E44 Only)

Table 13. DC Electrical Characteristics T_A = 0 °C to +70 °C, 12 MHz

No.	Symbol	Parameter	V_{CC} [1]	Min	Max	Units	Notes
1	TdA(AS)	Address Valid to $\overline{AS}$ Rise Delay	3.5V	35		ns	2
			5.5V	35		ns	2
2	TdAS(A)	$\overline{AS}$ Rise to Address Float Delay	3.5V	45		ns	2
			5.5V	45		ns	2
3	TdAS(DR)	$\overline{AS}$ Rise to Read Data Req'd Valid	3.5V		250	ns	2,3
			5.5V		250	ns	2,3

Table 14. DC Electrical Characteristics T_A = -40 °C to +105 °C, 12 MHz (Continued)

No.	Symbol	Parameter	V_{CC}[1]	Min	Max	Units	Notes
10	TdDS(A)	$\overline{DS}$ Rise to Address Active Delay	4.5V	45		ns	2
			5.5V	55		ns	2
11	TdDS(AS)	$\overline{DS}$ Rise to $\overline{AS}$ Fall Delay	4.5V	45		ns	2
			5.5V	45		ns	2
12	TdR/W(AS)	R/$\overline{W}$ Valid to $\overline{AS}$ Rise Delay	4.5V	45		ns	2
			5.5V	45		ns	2
13	TdDS(R/W)	$\overline{DS}$ Rise to R/$\overline{W}$ Not Valid	4.5V	45		ns	2
			5.5V	45		ns	2
14	TdDW(DSW)	Write Data Valid to $\overline{DS}$ Fall (Write) Delay	4.5V	55		ns	2
			5.5V	55		ns	2
15	TdDS(DW)	$\overline{DS}$ Rise to Write Data Not Valid Delay	4.5V	55		ns	2
			5.5V	55		ns	2
16	TdA(DR)	Address Valid to Read Data Req'd Valid	4.5V		310	ns	2,3
			5.5V		310	ns	2,3
17	TdAS(DS)	$\overline{AS}$ Rise to $\overline{DS}$ Fall Delay	4.5V	65		ns	2
			5.5V	65		ns	2
18	TdDM(AS)	$\overline{DM}$ Valid to $\overline{AS}$ Rise Delay	4.5V	35		ns	2
			5.5V	35		ns	2
19	ThDS(AS)	$\overline{DS}$ Valid to Address Valid Hold Time	4.5V	35		ns	2
			5.5V	35		ns	2

Notes

1. The V_{CC} voltage specification of 5.5 V guarantees 5.0 V ± 0.5 V and the V_{CC} voltage specification of 3.5 V guarantees only 3.5 V.
2. Timing numbers given are for minimum TpC.
3. When using extended memory timing, add 2 TpC.

Standard Test Load

All timing references use 0.7 V_{CC} for a logic 1 and 0.2 V_{CC} for a logic 0.

For Standard Mode (not Low-EMI Mode for outputs) with SMR, D1 = 0, D0 = 0.

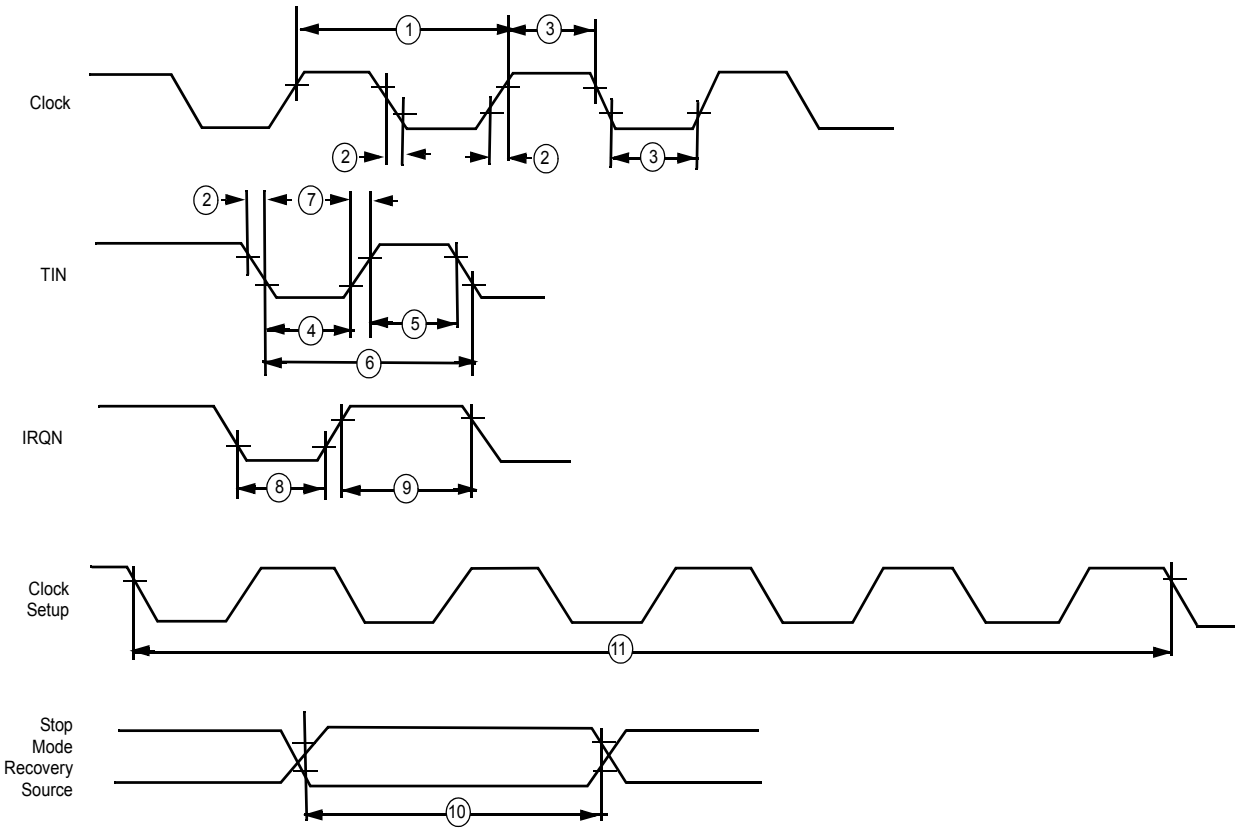


Figure 15. Additional Timing Diagram

Table 15. Additional Timing Table (Divide-By-One Mode) T_A = 0 °C to +70 °C

No	Symbol	Parameter	V_{CC} [1]	Min	Max	Min	Max	Units	Notes
1	TpC	Input Clock Period	3.5V	250	DC	166	DC	ns	2,3,4
			5.5V	250	DC	166	DC	ns	2,3,4
2	TrC,TfC	Clock Input Rise & Fall Times	3.5V		25		25	ns	2,3,4
			5.5V		25		25	ns	2,3,4
3	TwC	Input Clock Width	3.5V	100		100		ns	2,3,4
			5.5V	100		100		ns	2,3,4
4	TwTinL	Timer Input Low Width	3.5V	100		100		ns	2,3,4
			5.5V	70		70		ns	2,3,4

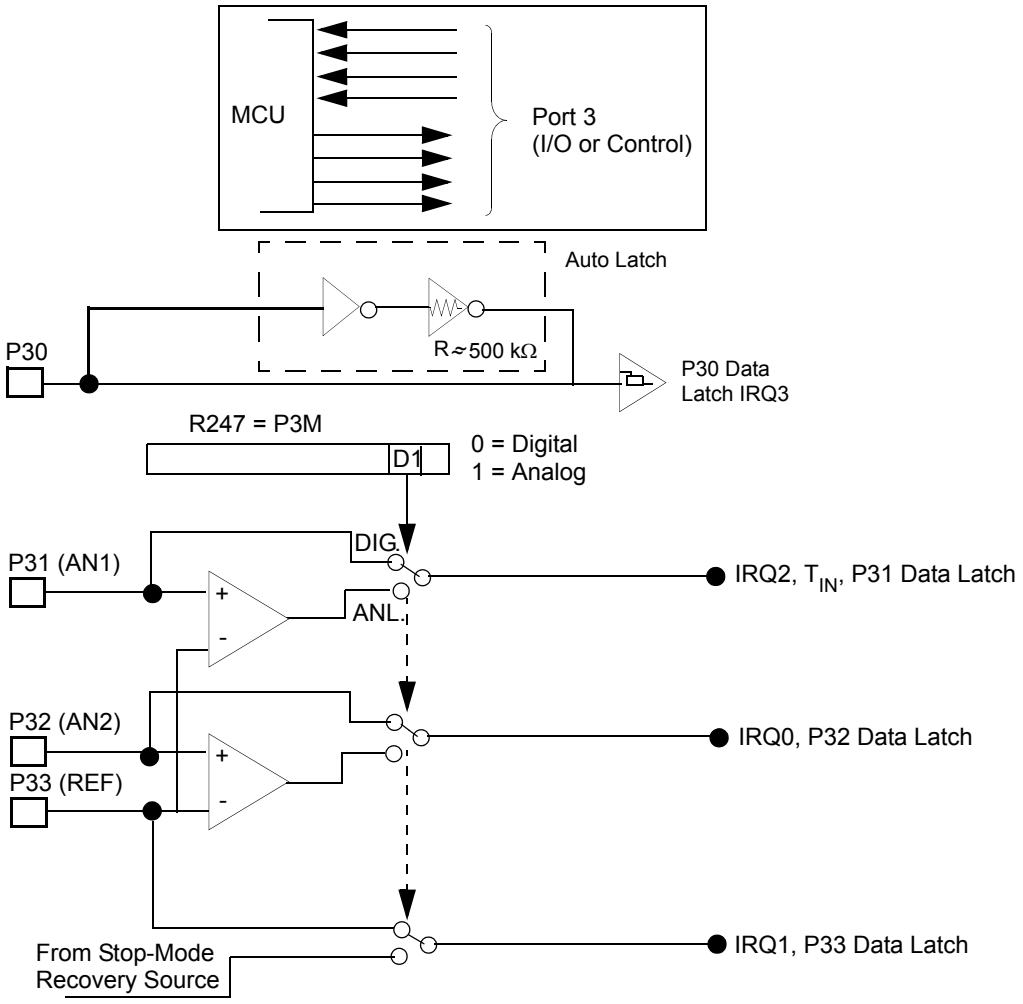


Figure 21. Port 3 Configuration

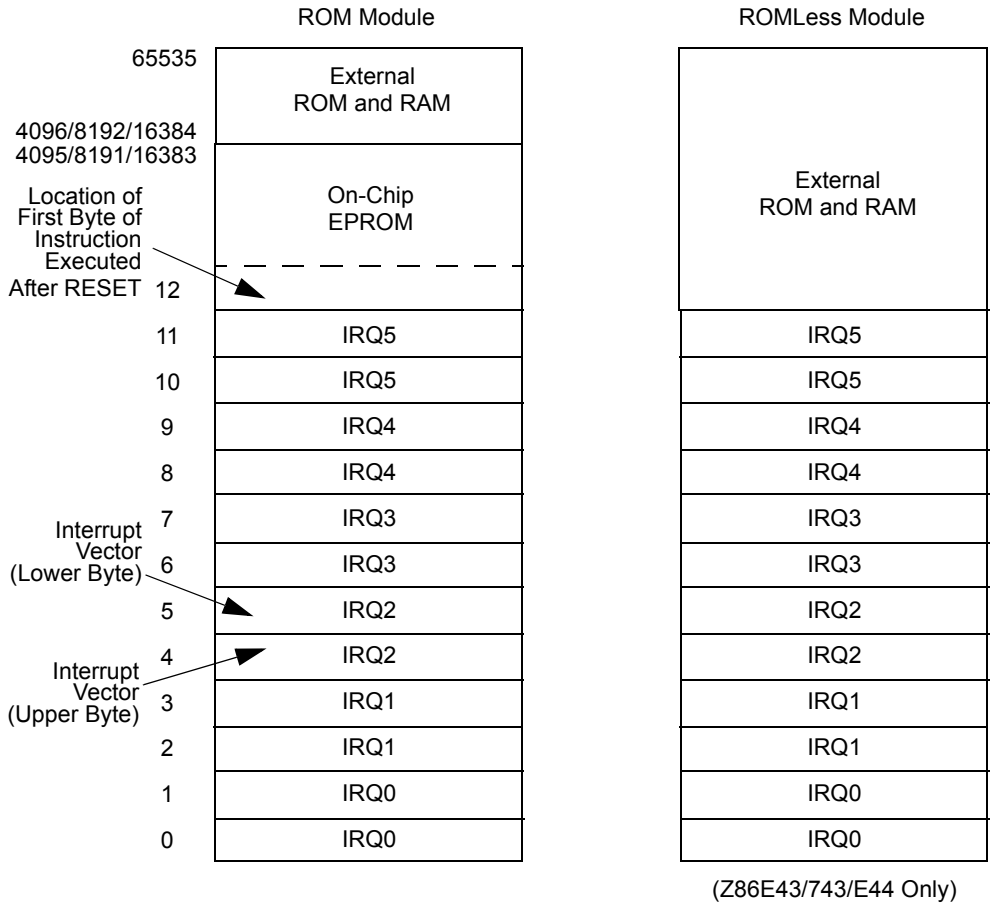


Figure 22. Program Memory Map

EPROM Protect. When in ROM Protect Mode, and executing out of External Program Memory, instructions LDC, LDCI, LDE, and LDEI cannot read Internal Program Memory.

When in EPROM Protect Mode and executing out of Internal Program Memory, instructions LDC, LDCI, LDE, and LDEI can read Internal Program Memory.

Data Memory ($\overline{DM}$). In ROM Mode, the Z86E43/743/E44 can address up to 60156/48 KB of external data memory beginning at location 4096/8192/16384. In ROMless mode, the Z86E43/743/E44 can address up to 64 KB of data memory. External data memory may be included with, or separated from, the external program memory space. $\overline{DM}$, an optional I/0 function that can be programmed to appear on pin P34, is used to distinguish between data and program memory space (Figure 23). The state of the $\overline{DM}$ signal is controlled by the type of instruction being executed. An LDC opcode references PROGRAM ($\overline{DM}$ inactive) memory, and an LDE instruction references data ($\overline{DM}$ active Low) memory.

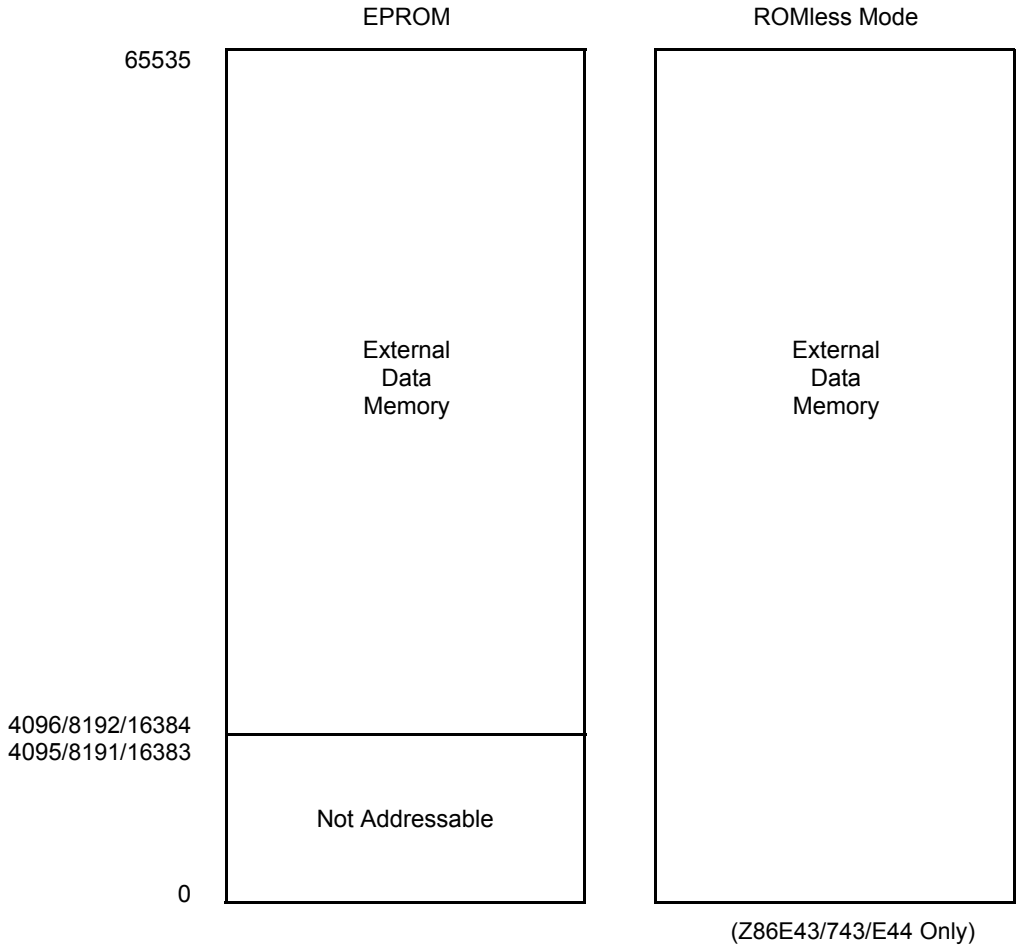


Figure 23. Data Memory Map

Register File. The register file consists of three I/O port registers, 236/125 general-purpose registers, 15 control and status registers, and three system configuration registers in the expanded register group. The instructions can access registers directly or indirectly through an 8-bit address field. This allows a short 4-bit register address using the Register Pointer (see Figure 24). In the 4-bit mode, the register file is divided into 16 working register groups, each occupying 16 continuous locations. The Register Pointer addresses the starting location of the active working-register group.

Note: *Register Group E0-EF can only be accessed through working register and indirect addressing modes.*

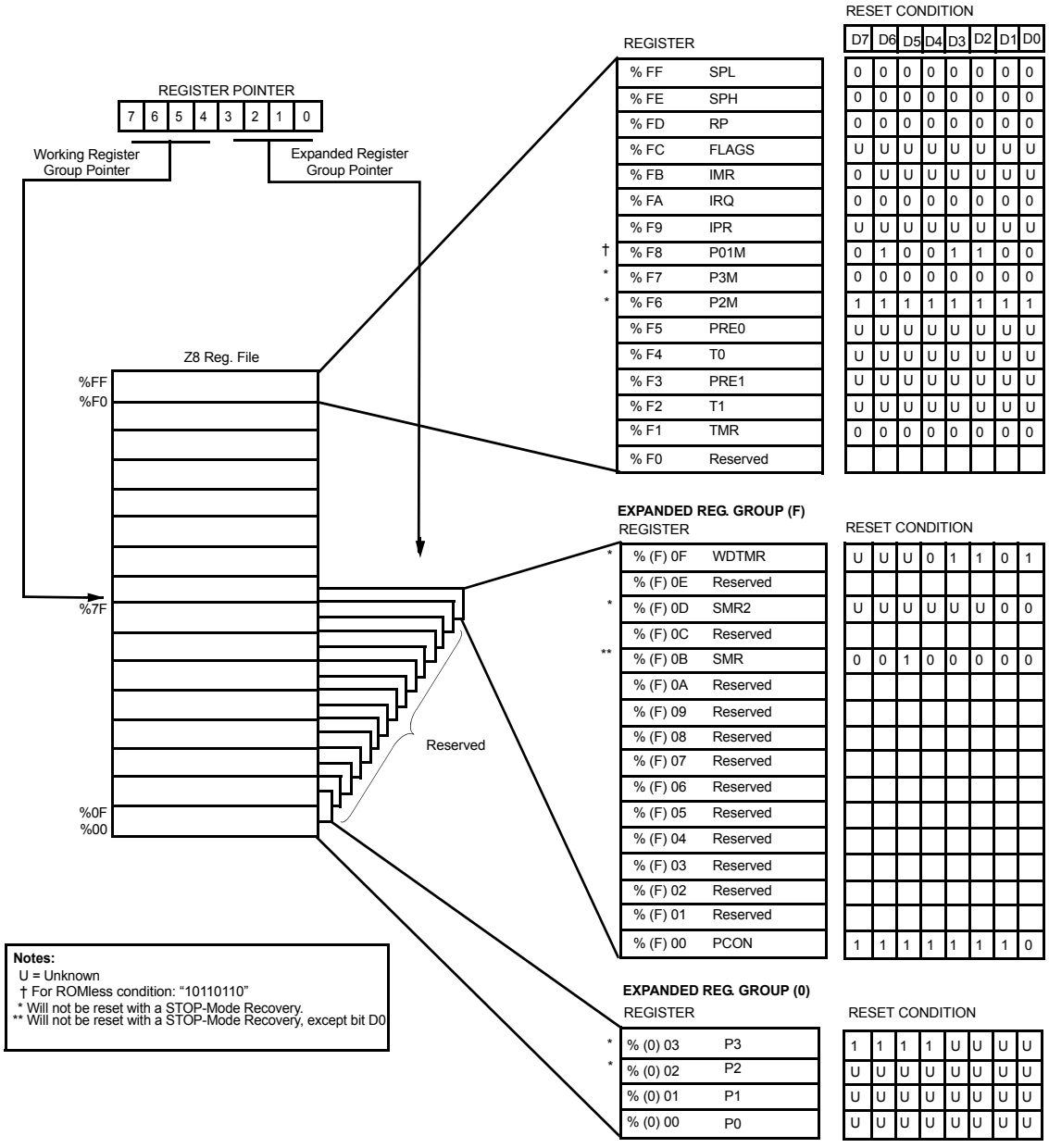


Figure 26. Expanded Register File Architecture

General-Purpose Registers (GPR). These registers are undefined after the device is powered up. The registers keep their last value after any reset, as long as the reset occurs in the V_{CC} voltage-specified operating range. The register R254 is general-purpose on Z86E33/733/E34. R254 and R255 are set to 00h after any reset or Stop Mode Recovery.

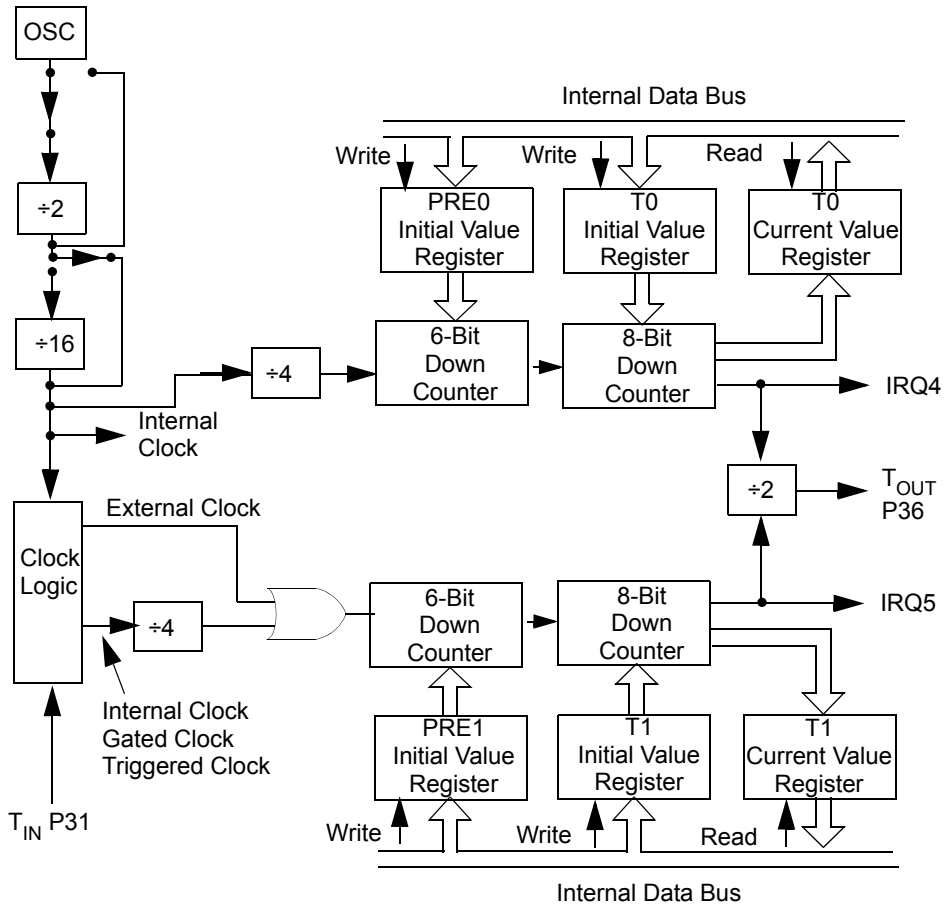


Figure 27. Counter/Timer Block Diagram

Interrupts. The MCU has six different interrupts from six different sources. The interrupts are maskable and prioritized (Figure 28). The six sources are divided as follows: four sources are claimed by Port 3 lines P33-P30) and two in counter/timers. The Interrupt Mask Register globally or individually enables or disables the six interrupt requests (Table 20).

When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority Register (IPR). An interrupt machine cycle is activated when an interrupt request is granted. Thus, disabling all subsequent interrupts, saves the Program Counter and Status Flags, and then branches to the program memory vector location reserved for that interrupt. All interrupts are vectored through locations in the program memory. This memory location and the next byte contain the 16-bit starting address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the interrupt request register is polled to determine which of the interrupt requests need service.

An interrupt resulting from AN1 is mapped into IRQ2, and an interrupt from AN2 is mapped into IRQ0. Interrupts IRQ2 and IRQ0 may be rising, falling or both edge triggered, and are programmable by the user. The software may poll to identify the state of the pin.

Programming bits for the Interrupt Edge Select are located in bits D7 and D6 of the IRQ Register (R250). The configuration is shown in Table 21.

Table 21. IRQ Register Configuration

IRO		Interrupt Edge	
D7	**D6**	**P31**	**P32**
0	0	F	F
0	1	F	R
1	0	R	F
1	1	R/F	R/F

Notes
1. F = Falling Edge
2. R = Rising Edge

Clock. The on-chip oscillator has a high-gain, parallel-resonant amplifier for connection to a crystal, RC, ceramic resonator, or any suitable external clock source (XTAL1 = Input, XTAL2 = Output). The crystal should be AT cut, 10 kHz to 16 MHz max, with a series resistance (RS) less than or equal to 100 Ω.

The crystal should be connected across XTAL1 and XTAL2 using the vendor's recommended capacitor values from each pin directly to device pin Ground. The RC oscillator option can be selected in the programming mode. The RC oscillator configuration must be an external resistor connected from XTAL1 to XTAL2, with a frequency-setting capacitor from XTAL1 to Ground (Table 29).

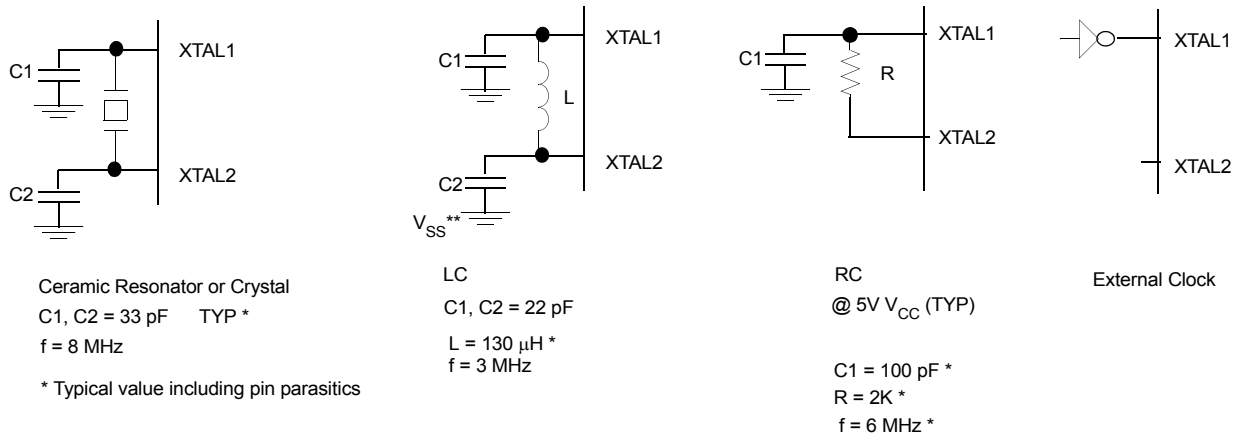


Figure 29. Oscillator Configuration

Power-On Reset (POR). A timer circuit clocked by a dedicated on-board RC oscillator is used for the Power-On Reset (POR) timer function. The POR timer allows V_{CC} and the oscillator circuit to stabilize before instruction execution begins.

The POR timer circuit is a one-shot timer triggered by one of three conditions:

1. Power fail to Power OK status
2. Stop Mode Recovery (if D5 of SMR=0)
3. WDT time-out

The POR time is a nominal 5 ms. Bit 5 of the STOP mode Register (SMR) determines whether the POR timer is by-passed after Stop Mode Recovery (typical for an external clock and RC/LC oscillators with fast start up times).

HALT. Turns off the internal CPU clock, but not the XTAL oscillation. The counter/timers and external interrupt IRQ0, IRQ1, and IRQ2 remain active. The device is recovered by interrupts, either externally or internally generated. An interrupt request must be executed (enabled) to exit HALT Mode. After the interrupt service routine, the program continues from the instruction after the HALT. In order to enter STOP or HALT Mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, you must execute a NOP (Opcode = FFh) immediately before the appropriate sleep instruction, that is:

```
FF    NOP    ; clear the pipeline
6F    STOP   ; enter STOP mode
```

or

```
FF    NOP    ; clear the pipeline
7F    HALT   ; enter HALT mode
```

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 microamperes or less. STOP Mode is terminated by one of the following resets: either by WDT time-out, POR, a Stop Mode Recovery Source, which is defined by the SMR register or external reset. This causes the processor to restart the application program at address 000Ch.

Port Configuration Register (PCON). The PCON register configures the ports individually; comparator output on Port 3, open-drain on Port 0 and Port 1, low EMI on Ports 0, 1, 2 and 3, and low EMI oscillator. The PCON register is located in the expanded register file at Bank F, location 00 (Figure 30).

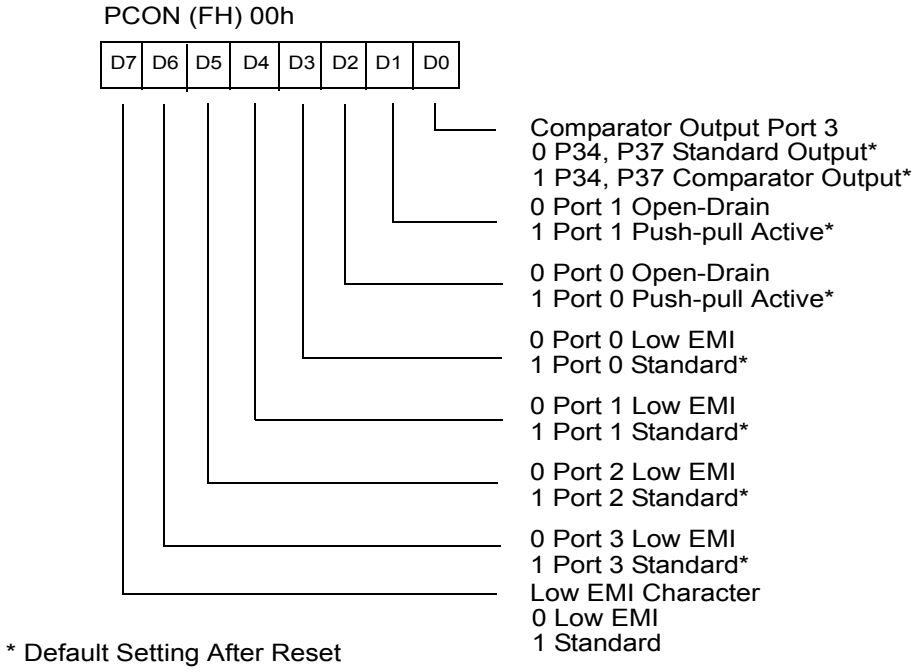
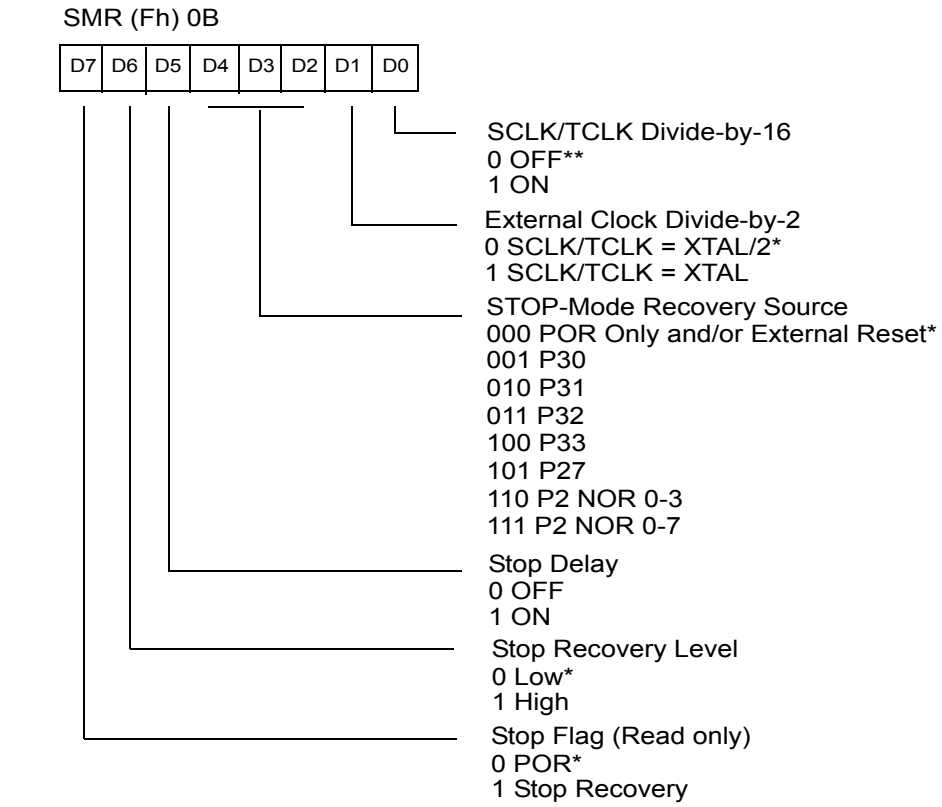


Figure 30. Port Configuration Register (PCON) (Write Only)



Note: Note used in conjunction with SMR2 Source
* Default setting after RESET
** Default setting after RESET and STOP-Mode Recovery

Figure 37. Stop Mode Recovery Register (Write Only Except Bit D7, Which is Read Only)

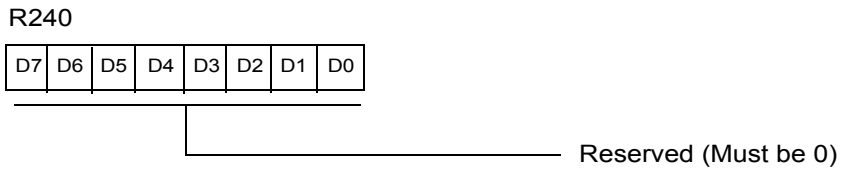


Figure 40. Reserved

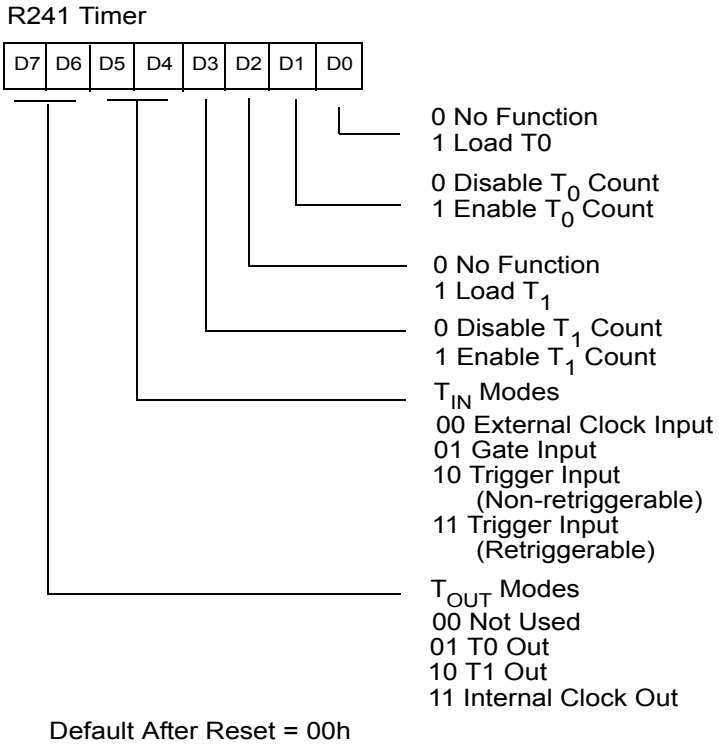
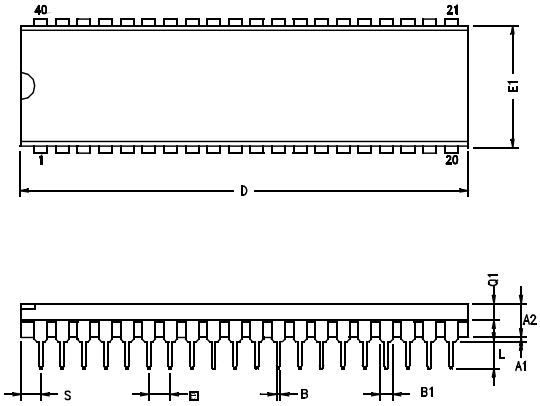


Figure 41. Timer Mode Register ($F1_h$: Read/Write)

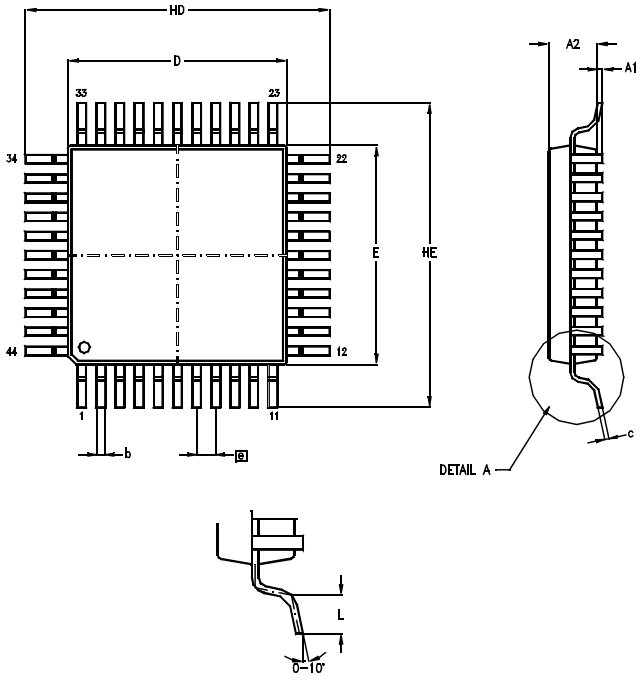
Package Information



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	1.02	.020	.040
A2	3.18	3.94	.125	.155
B	0.38	0.53	.015	.021
B1	1.02	1.52	.040	.060
C	0.23	0.38	.009	.015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
e	2.54 TYP		.100 TYP	
eA	15.49	16.76	.610	.660
L	3.05	3.81	.120	.150
Q1	1.40	1.91	.055	.075
S	1.52	2.29	.060	.090

CONTROLLING DIMENSIONS : INCH

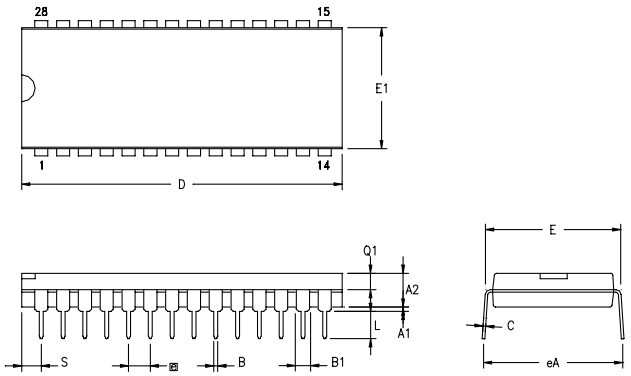
Figure 56. 40-PIN DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.05	0.25	.002	.010
A2	2.00	2.25	.078	.089
b	0.25	0.45	.010	.018
c	0.13	0.20	.005	.008
HD	13.70	14.15	.539	.557
D	9.90	10.10	.390	.398
HE	13.70	14.15	.539	.557
E	9.90	10.10	.390	.398
e	0.80 BSC		.0315 BSC	
L	0.60	1.20	.024	.047

NOTES:
1. CONTROLLING DIMENSIONS : MILLIMETER
2. LEAD COPLANARITY : MAX .10 .004"

Figure 57. 44-PIN LQFP Package Diagram

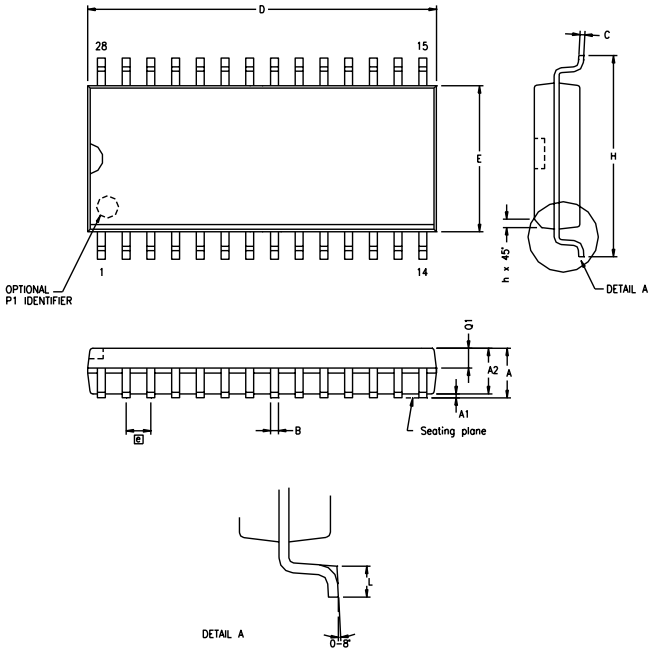


SYMBOL	OPT #	MILLIMETER		INCH	
		MIN	MAX	MIN	MAX
A1		0.38	1.02	.015	.040
A2		3.18	4.19	.125	.165
B		0.38	0.53	.015	.021
B1	01	1.40	1.65	.055	.065
	02	1.14	1.40	.045	.055
C		0.23	0.38	.009	.015
D	01	36.58	37.34	1.440	1.470
	02	35.31	35.94	1.390	1.415
E		15.24	15.75	.600	.620
E1	01	13.59	14.10	.535	.555
	02	12.83	13.08	.505	.515
e		2.54 TYP		.100 TYP	
eA		15.49	16.76	.610	.660
L		3.05	3.81	.120	.150
Q1	01	1.40	1.91	.055	.075
	02	1.40	1.78	.055	.070
S	01	1.52	2.29	.060	.090
	02	1.02	1.52	.040	.060

CONTROLLING DIMENSIONS : INCH

OPTION TABLE	
OPTION #	PACKAGE
01	STANDARD
02	IDF

Figure 58. 28-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.64	.094	.104
A1	0.10	0.30	.004	.012
A2	2.24	2.44	.088	.096
B	0.36	0.46	.014	.018
C	0.23	0.30	.009	.012
D	17.78	18.00	.700	.710
E	7.40	7.60	.291	.299
e	1.27 BSC		.050 BSC	
H	10.00	10.65	.394	.419
h	0.30	0.71	.012	.028
L	0.61	1.00	.024	.039
Q1	0.97	1.09	.038	.043

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 59. 28-Pin SOIC Package Diagram

Ordering Information

Table 24.Ordering Information

Product	Speed (MHz)	Package Type	Pin Count
Z86E3312PSC	12	PDIP	28
Z86E3312SCC	12	SOIC	28
Z86E3312PSC	12	PLCC	28
Z86E3412PEC	12	PDIP	28
Z86E3412PSC	12	PDIP	28
Z86E3412SSC	12	SOIC	28
Z86E3412VSC	12	PLCC	28
Z86E4312FSC	12	LQFP	44
Z86E4312PSC	12	PDIP	40
Z86E4312VSC	12	PLCC	44
Z86E4412FSC	12	LQFP	44
Z86E4412PEC	12	PDIP	40
Z86E4412PSC	12	PDIP	40
Z86E4412VSC	12	PLCC	44
Z8673312PSC	12	PDIP	28
Z8673312SSC	12	SOIC	28
Z8673312VSC	12	PLCC	28
Z8674312FSC	12	LQFP	44
Z8674312PSC	12	PDIP	40
Z8674312VSC	12	PLCC	44